


| PCN Number: | 20151027001 | | PCN Date: | 10/30/2015 | | | | | | | | | | | | |
|--|---|---------------------------------------|--|-------------------------------------|--|-------|------|-----------------------|----------|----------------------|----------------------|---------------|----------------|-----------------------|--------------|---------------------|
| Title: | Qualification of NFME Additional Assembly & Test site for Select TO220 Packaged Devices | | | | | | | | | | | | | | | |
| Customer Contact: | PCN Manager | Dept: | Quality Services | | | | | | | | | | | | | |
| Proposed 1st Ship Date: | 1/30/2016 | Estimated Sample Availability: | Provided upon Request | | | | | | | | | | | | | |
| Change Type: | | | | | | | | | | | | | | | | |
| <input checked="" type="checkbox"/> | Assembly Site | <input type="checkbox"/> | Assembly Process | <input checked="" type="checkbox"/> | | | | | | | | | | | | |
| <input type="checkbox"/> | Design | <input type="checkbox"/> | Electrical Specification | <input type="checkbox"/> | | | | | | | | | | | | |
| <input checked="" type="checkbox"/> | Test Site | <input type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | | | | | | | | | | | | |
| <input type="checkbox"/> | Wafer Bump Site | <input type="checkbox"/> | Wafer Bump Material | <input type="checkbox"/> | | | | | | | | | | | | |
| <input type="checkbox"/> | Wafer Fab Site | <input type="checkbox"/> | Wafer Fab Materials | <input type="checkbox"/> | | | | | | | | | | | | |
| | | <input type="checkbox"/> | Part number change | | | | | | | | | | | | | |
| PCN Details | | | | | | | | | | | | | | | | |
| Description of Change: | | | | | | | | | | | | | | | | |
| <p>Texas Instruments is pleased to announce the qualification of Nantong Fujitsu Microelectronics (NFME) as an additional Assembly & Test site for select devices in the TO220 package shown in the table below. BOM differences are noted as follows:</p> <table border="1" style="width: 100%;"> <thead> <tr> <th></th> <th>ASEWH</th> <th>NFME</th> </tr> </thead> <tbody> <tr> <td>Mount Compound</td> <td>SID#A-11</td> <td>SID#1110999A2</td> </tr> <tr> <td>Mold Compound</td> <td>SID#4020026A3</td> <td>SID#R12</td> </tr> <tr> <td>Gate Bond Wire</td> <td>Al, 3.0 mils</td> <td>Al, 5.0 mils</td> </tr> </tbody> </table> <p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p> | | | | | | ASEWH | NFME | Mount Compound | SID#A-11 | SID#1110999A2 | Mold Compound | SID#4020026A3 | SID#R12 | Gate Bond Wire | Al, 3.0 mils | Al, 5.0 mils |
| | ASEWH | NFME | | | | | | | | | | | | | | |
| Mount Compound | SID#A-11 | SID#1110999A2 | | | | | | | | | | | | | | |
| Mold Compound | SID#4020026A3 | SID#R12 | | | | | | | | | | | | | | |
| Gate Bond Wire | Al, 3.0 mils | Al, 5.0 mils | | | | | | | | | | | | | | |
| Reason for Change: | | | | | | | | | | | | | | | | |
| Continuity of Supply | | | | | | | | | | | | | | | | |
| Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): | | | | | | | | | | | | | | | | |
| None | | | | | | | | | | | | | | | | |
| Anticipated impact on Material Declaration | | | | | | | | | | | | | | | | |
| <input type="checkbox"/> | No Impact to the Material Declaration | <input checked="" type="checkbox"/> | Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website . | | | | | | | | | | | | | |
| Changes to product identification resulting from this PCN: | | | | | | | | | | | | | | | | |
| Assembly Site | Assembly Site Origin (22L) | Assembly Country Code (21L) | Assembly City | | | | | | | | | | | | | |
| ASEWH | AWH | CHN | Weihai | | | | | | | | | | | | | |
| NFME | NFM | CHN | Economic Development Zone | | | | | | | | | | | | | |

Sample product shipping label (not actual product label)

 **TEXAS
INSTRUMENTS**
MADE IN: Malaysia
2DC: 2Q:

| | |
|---------------------|----------|
| MSL '2 /260C/1 YEAR | SEAL DT |
| MSL 1 /235C/UNLIM | 03/29/04 |

OPT:
ITEM: 39
LBL: 5A (L)T0:1750


G4



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Topside Device marking:

Assembly site code for ASEWH= I

Assembly site code for NFME = E

Product Affected

CSD19505KCS

CSD19506KCS

CSD19535KCS

CSD19536KCS

Qualification Report

**Offload - 19505/19535/19506/19536 to NFME
Approve Date 25-Sep-2015**

Product Attributes

| Attributes | Qual Device: CSD19505KCS | Qual Device: CSD19506KCS | Qual Device: CSD19535KCS | Qual Device: CSD19536KCS |
|---------------------|-----------------------------|-----------------------------|-----------------------------|-----------------------------|
| Assembly Site | NFME | NFME | NFME | NFME |
| Package Family | TO-220 | TO-220 | TO-220 | TO-220 |
| Flammability Rating | UL-94V-0 | UL-94V-0 | UL-94V-0 | UL-94V-0 |
| Wafer Fab Supplier | CFAB | CFAB | CFAB | CFAB |
| Wafer Fab Process | N35UMV09L2P1M0C6 | N35UMV09L2P1M0C6 | N35UMV09L2P1M0C6 | N35UMV09L2P1M0C6 |

- QBS: Qual By Similarity
- Qual Device CSD19506KCS is qualified at NC-P
- Qual Device CSD19536KCS is qualified at NC-P
- Qual Device CSD19505KCS is qualified at NC-P
- Qual Device CSD19535KCS is qualified at NC-P

ASEWH KCS 80V & 100V Qualification Summary

| CSD19536KCS Qualification Test Summary | | | | |
|--|--|---------------|-------------------|---------|
| Stress | Conditions | Test Duration | Sample Size | Results |
| HTRB | 175°C/80% Rated Vds | 1K hrs | 3 lots x 77 units | Pass |
| HTGB | 175°C/80% Rated Vgs | 1K hrs | 3 lots x 77 units | Pass |
| THB | 85°C/85%R.H./80% Rated Vds | 1K hrs | 3 lots x 77 units | Pass |
| Autoclave | 121C/100% RH | 96 hrs | 3 lots x 77 units | Pass |
| Intermittent Op Life | Delta Tj = 100°C 2 min on/2 min off | 10K cycles | 3 lots x 77 units | Pass |
| Temp Cycle | -65°C to 150°C | 500 cycles | 3 lots x 77 units | Pass |

Pass = 0/77 x 3 lots

Preconditioning performed on devices prior to THB, Autoclave, & Temp Cycle stresses

- Bake: 24 hours @ 125°C
- 3X reflow + flux + rinse, 260°C Pb free reflow temp

The CSD19505KCS, CSD19506KCS & CSD19535KCS were qualified by similarity and verified by performing qualification tests to the conditions shown in the table below:

| CSD19505KCS, CSD19506KCS, & CSD19535KCS Qualification Test Summary | | | | |
|---|---------------------|----------------------|--------------------|----------------|
| Stress | Conditions | Test Duration | Sample Size | Results |
| HTRB | 175°C/80% Rated Vds | 168 hrs | 1 lot x 77 units | Pass |
| HTGB | 175°C/80% Rated Vgs | 168 hrs | 1 lot x 77 units | Pass |

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | Test Name / Condition | Duration | Qual Device: CSD19505KCS | Qual Device: CSD19506KCS | Qual Device: CSD19535KCS | Qual Device: CSD19536KCS |
|------|---------------------------------|----------------------------------|-----------------------------|-----------------------------|-----------------------------|-----------------------------|
| MQ | Manufacturability (Assembly) | (per mfg. Site specification) | 3/1/0 | 3/1/0 | 3/1/0 | 3/1/0 |

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|-----------------|--|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| Japan | PCNJapanContact@list.ti.com |